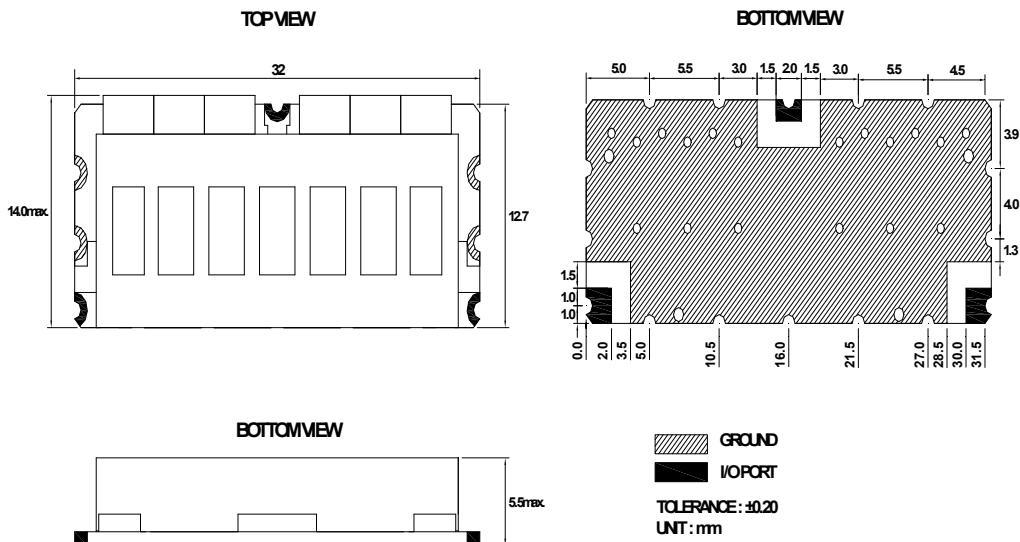


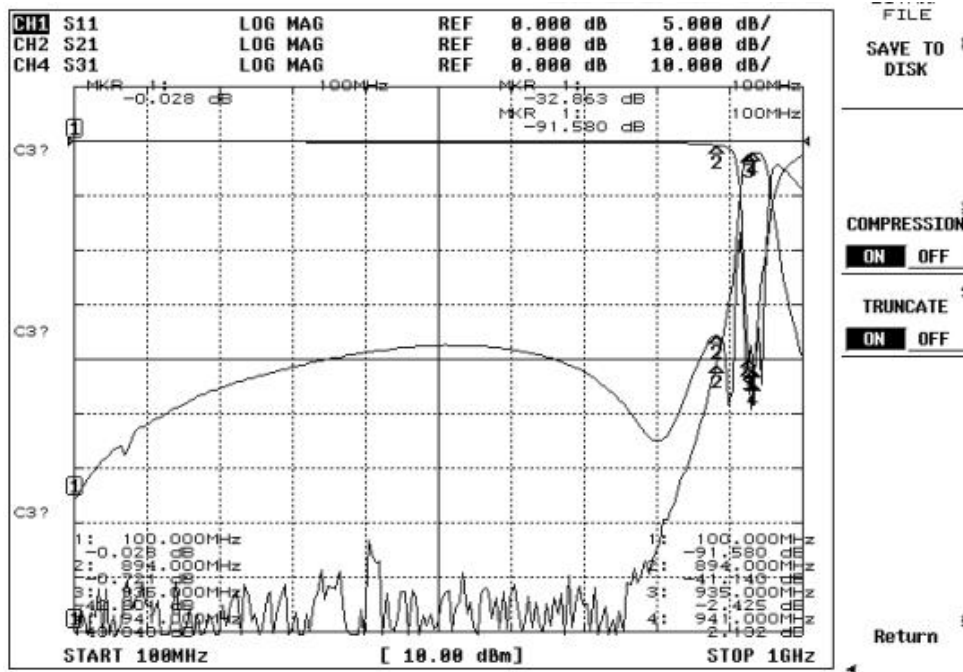
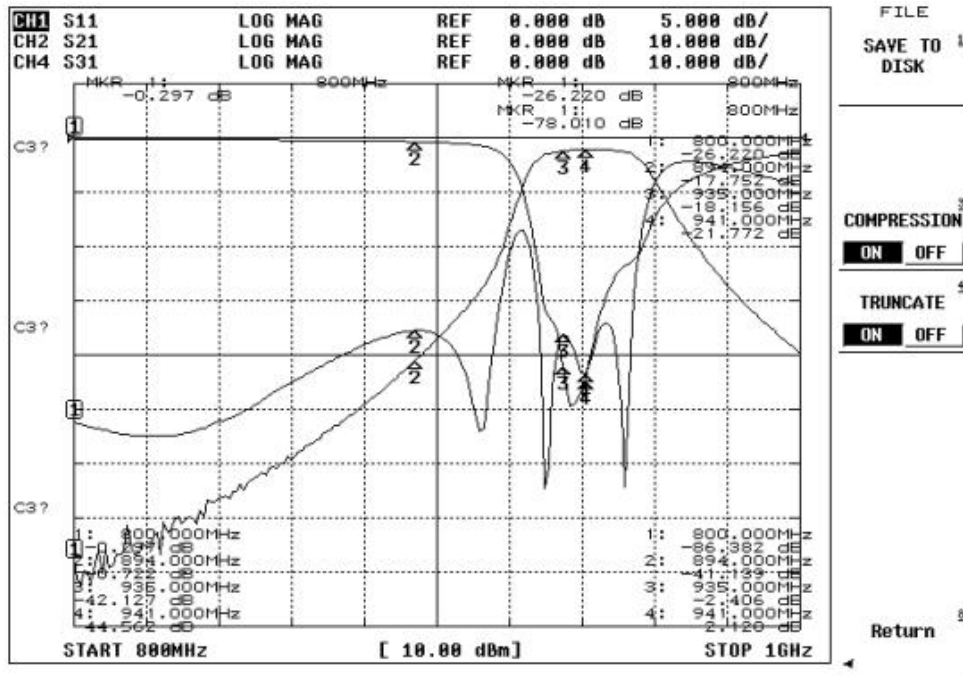
Electrical Specification

ITEMS	ANT >> Low	ANT >> High	UNIT
Center Frequency [fo]	397.0	938.0	MHz
Bandwidth [BW]	fo ± [100.0~849.0]	fo ±3.0 [935.0~941.0]	MHz
Insertion Loss in BW	1.0	2.5	dB max
Ripple in BW	0.8	0.6	dB max
Return Loss in BW	14.0	16.0	dB min
Attenuation <input checked="" type="checkbox"/> Absolute Value <input type="checkbox"/> Relative Value	40 dB min. @ [935~941]	40 dB min. @[100 ~ 849]	MHz
	dB min. @ [~]	dB min. @ [~]	MHz
	dB min. @ [~]	dB min. @ [~]	MHz
	dB min. @ [~]	dB min. @ [~]	MHz
Group Delay Variation			ns max
Input Power	1.0		W max.
In/Out Impedance	50 Ω		
Operation Temperature Range	-40°C to +85°C		

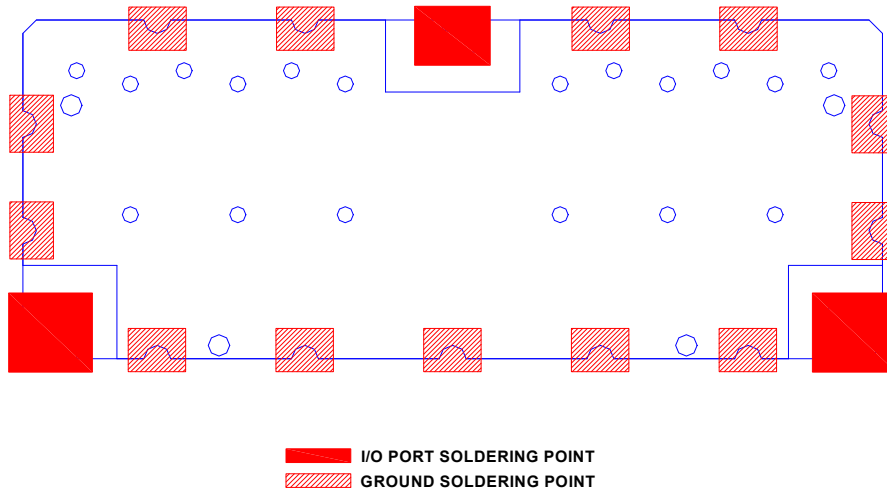
Mechanical Specification



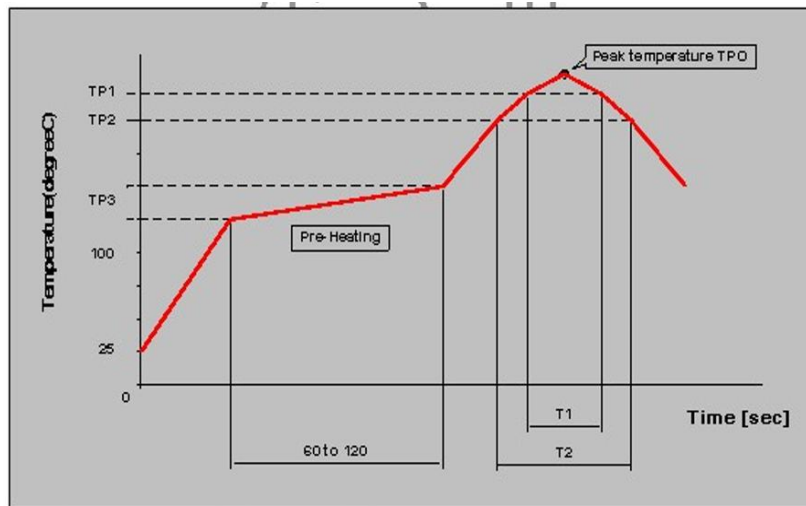
Plot Data



Recommneded PC Board Pattern



Soldering Condition



Measuring point of temperature : IN-OUT Terminals of The Device

Reflow Soldering : Both Convection and Infrared Rays, Hot Air and Hot Plate

Reflow standard condition	TPO (°C)	TP1 (°C)	T1 (s)	TP2 (°C)	T2 (s)	TP3 (°C)
Sn-3Ag-0.5 solder	245±5	220	30 to 60	—	—	150 to 180
Test condition of reflow heat resistance	260±5/0	240	20	220	70	150 to 180